

# MECHANICAL CASE OUTLINE

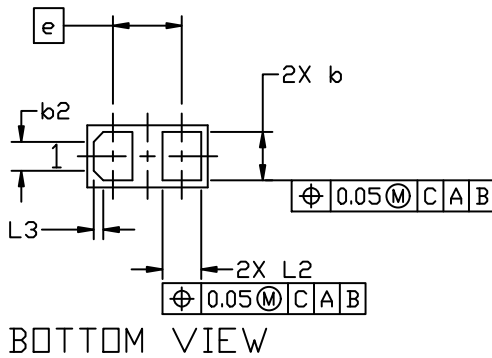
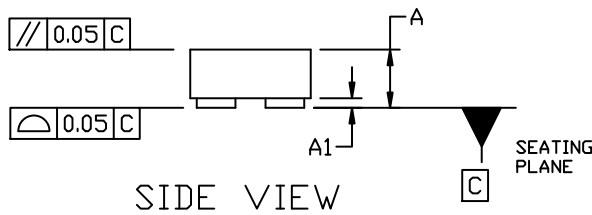
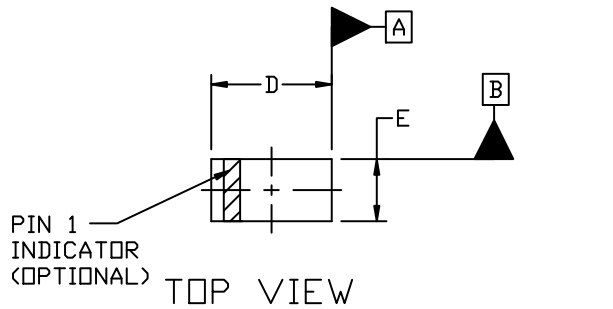
## PACKAGE DIMENSIONS



**X3DFN2, 0.62x0.32, 0.355P, (0201)**  
CASE 152AF  
ISSUE B

  
**SCALE 8:1**

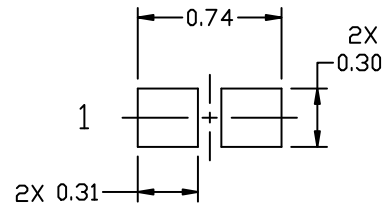
DATE 13 JAN 2023



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS

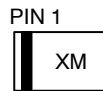
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.25	0.29	0.33
A1	0.00	---	0.05
b	0.22	0.25	0.28
b2	0.150 REF		
D	0.58	0.62	0.66
E	0.28	0.32	0.36
e	0.355 BSC		
L2	0.17	0.20	0.23
L3	0.050 REF		



**RECOMMENDED MOUNTING FOOTPRINT\***

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



X = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>X3DFN2, 0.62X0.32, 0.355P, (0201)</b>	<b>PAGE 1 OF 1</b>

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